2021 H1 Operation Briefing of Nan Ya PCB Corp.

August 12th 2021

Disclaimer

The description of historical events might include the information that was not reviewed by accountants. Thus, it might be insufficient to fully exhibit the financial status or operation results of Nan Ya PCB Corp.

The actual operation results, financial status, and sales outlook in the future might be different from what will be indicated or implied in this meeting. The reasons may be including but not limited to the market demand, price fluctuation, competition dynamic, global economy, supply-chain, foreign exchange rate, and other risks that the Company cannot control.

Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

Agenda

- **Company Profile**
- **Financial Status**
- **Future Product Development**
- **Operational Goals**

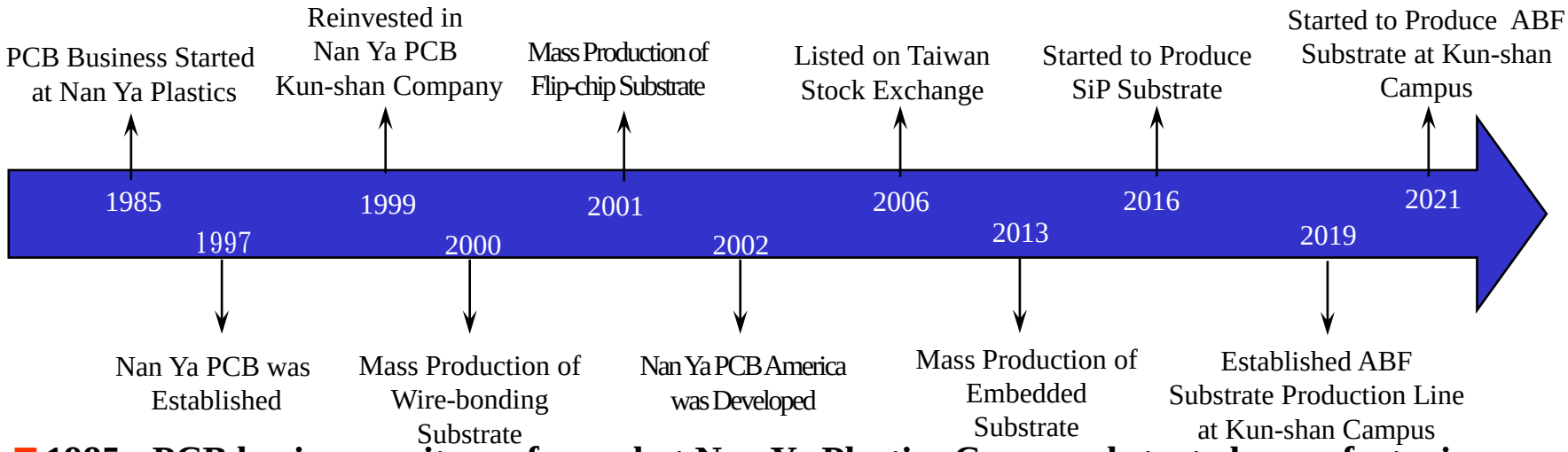
Company Profile

Business Overview

- **Subsidiary Company of Nan Ya Plastics Corp.**
- **Manufacture and Sell PCBs and IC Substrates**
- **2021 H1 Consolidated Revenues: NTD 23.3 Billion**
- **Market Value: NTD 251.6 Billion(June 30th 2021)**
- **Production Locations：Taiwan and China**

Company Profile

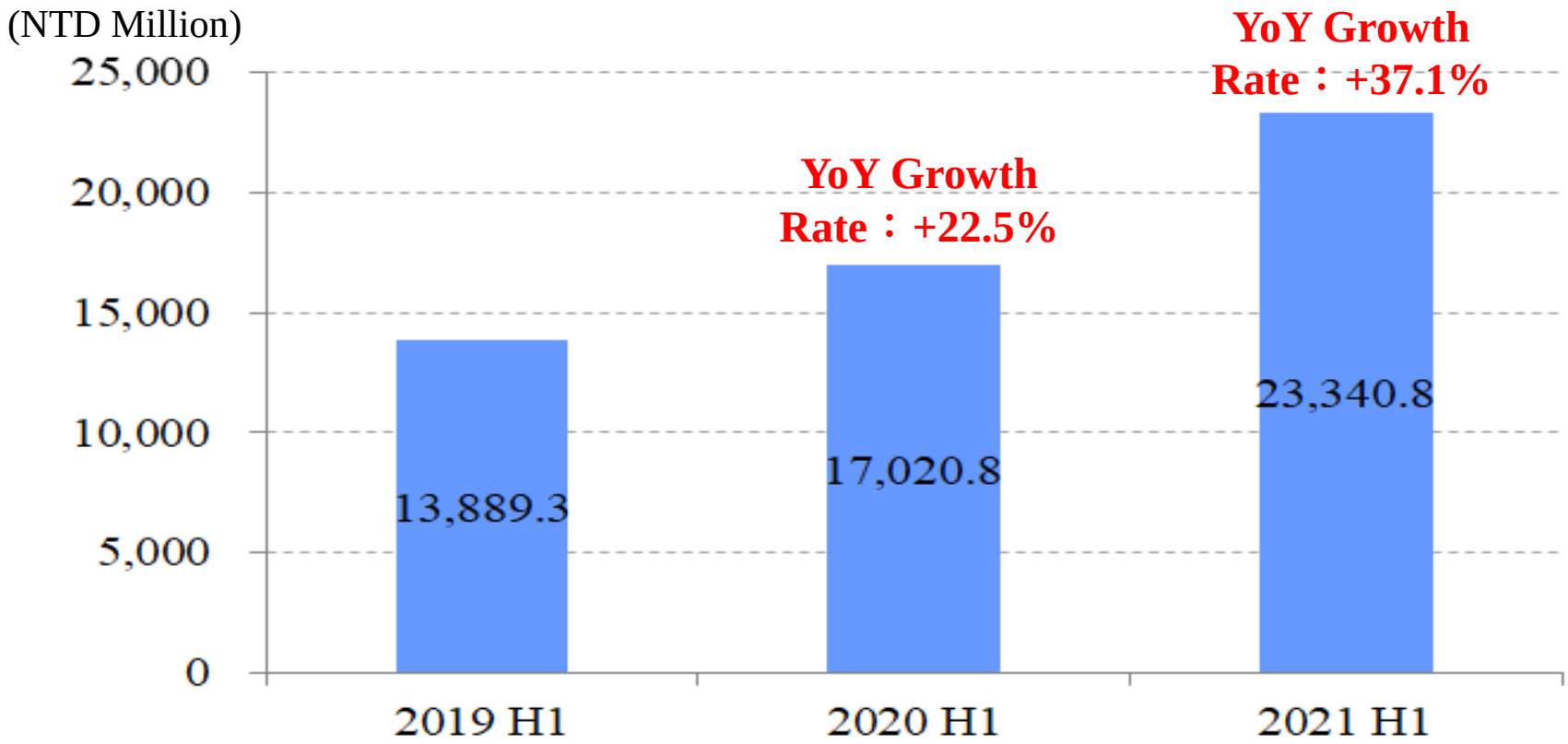
Milestone



- **1985 : PCB business unit was formed at Nan Ya Plastics Corp. and started manufacturing PCBs**
- **1997 : Approved by the Board of Nan Ya Plastics, Nan Ya PCB Corp. was established via reinvestment**
- **1999 : Reinvested Nan Ya PCB Kun-shan Company with capital of USD29.8 million**
- **2000 : Started manufacturing wire-bonding substrates**
- **2001 : Upgraded technologies and produced flip-chip substrates**
- **2002 : Established Nan Ya PCB America Corp.**
- **2006 : Listed on Taiwan Stock Exchange with ticker 8046 TT**
- **2013 : Upgraded technologies and produced Embedded substrates**
- **2016 : Started to produce System in Package (SiP) substrates**
- **2019 : In response to market demand, Nan Ya PCB Corp. started to build ABF substrate production line at Kun-shan Campus**
- **2021 : Kun-shan Campus started to manufacture ABF substrates**

Financial Status

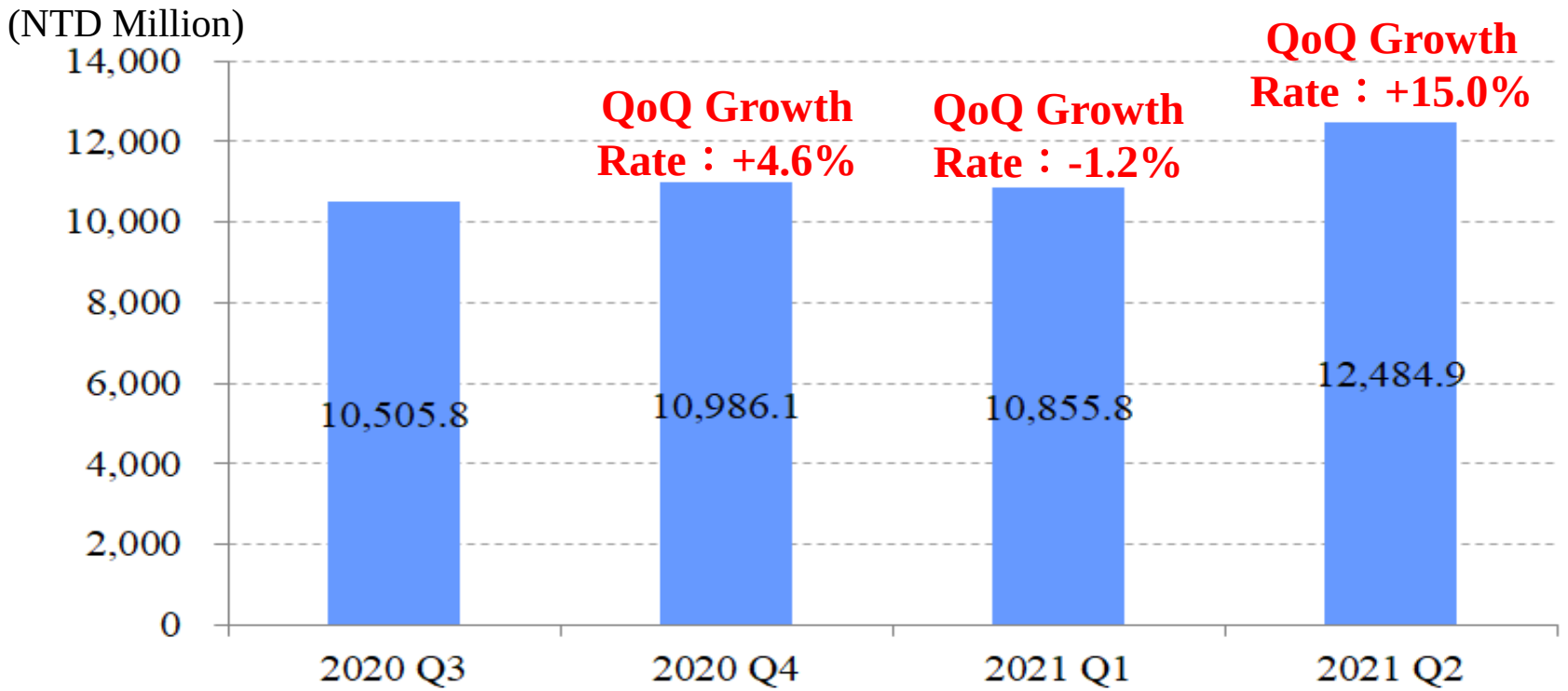
H1 Consolidated Revenues(IFRS) in Last 3 Years



- **Revenues in 2020 H1 were 22.5% greater than those in 2019 H1:**
  Nan Ya PCB was an early entrant in high-end telecom and SiP substrate fields and benefited from the increase in customer demands, and the 2020 revenues grew significantly from 2019.
- **Revenues in 2021 H1 were 37.1% greater than those in 2020 H1**
  Nan Ya PCB was helped by WFH and stay home entertainments, and the 2021 H1 performance was better than that in 2020 H1.

Financial Status

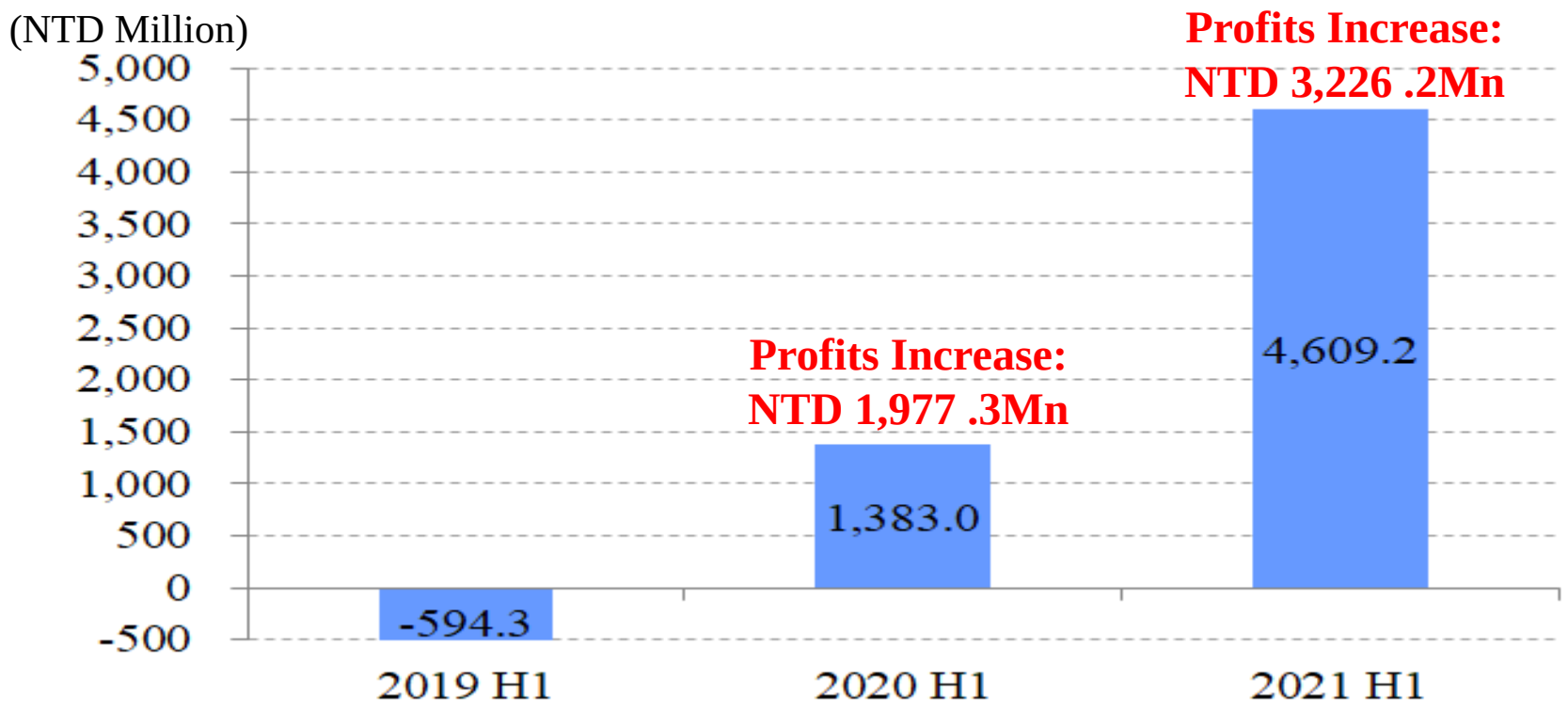
Quarterly Consolidated Revenues(IFRS) in a Year



- **Revenues in 20Q4 were 4.6% greater than those in 20Q3:**
  Increasing demands in the PC, telecom, and automotive electronics boosted the Q4 revenues and achieved our goal, consecutive growth of quarterly revenues.
- **Revenues in 21Q1 were 1.2% lower than those in 20Q4:**
  Because of fewer working days, revenues in 21Q1 slightly decreased from 20Q4.
- **Revenues in 21Q2 were 15.0% greater than those in 21Q1:**
  Due to the contribution from better product mix and the new IC substrate capacities at Kunshan Campus, revenues in 21Q2 increased from 21Q1.

Financial Status

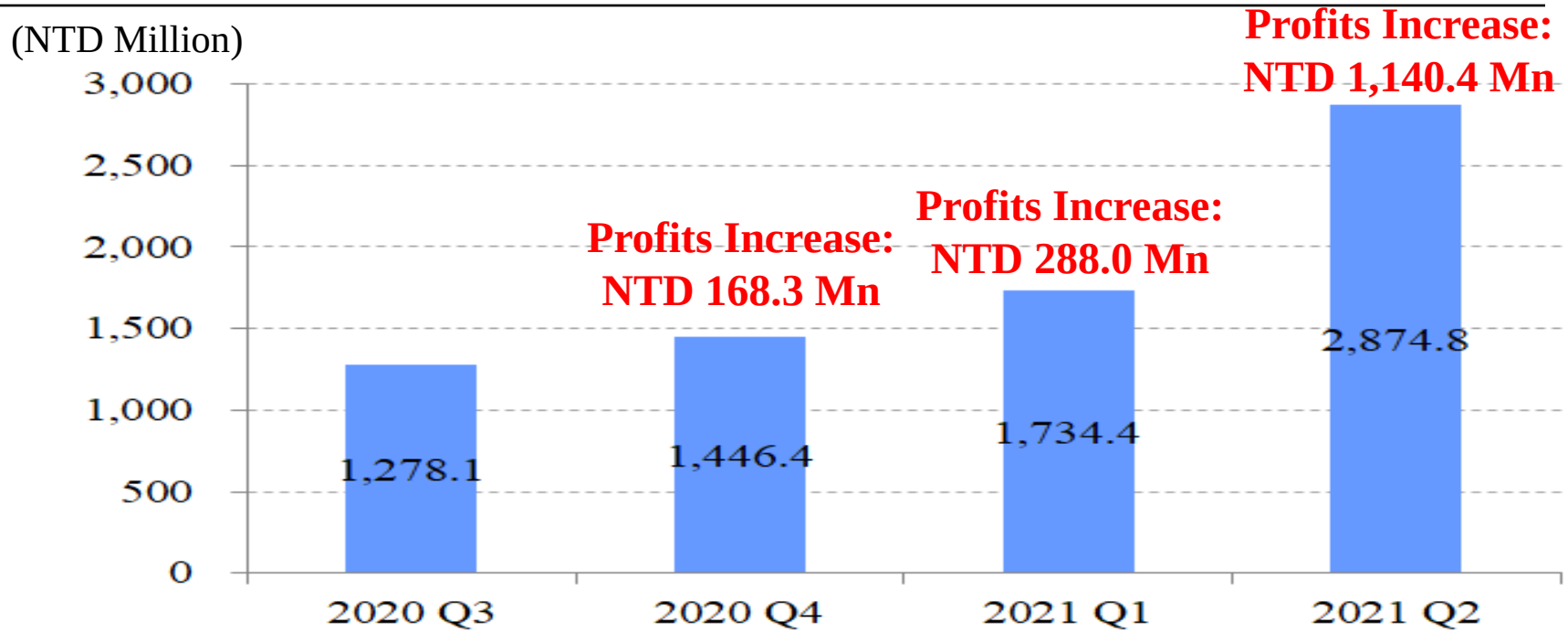
H1 Operation Profits(Losses) in Last 3 Years



- **Operation profits in 2020 H1 were increasing NTD 1,977.3 Mn from 2019 H1:**
  The 2020 H1 operation profits grew significantly because of improved yield rate and better product mix due to more high-end telecom products.
- **Operation profits in 2021 H1 were increasing NTD 3,226.2 Mn from 2020 H1:**
  In addition to the contribution from the better product mix and the new IC substrate capacities at Kunshan Campus, we applied AI to manufacturing management to enhance production and profits.

Financial Status

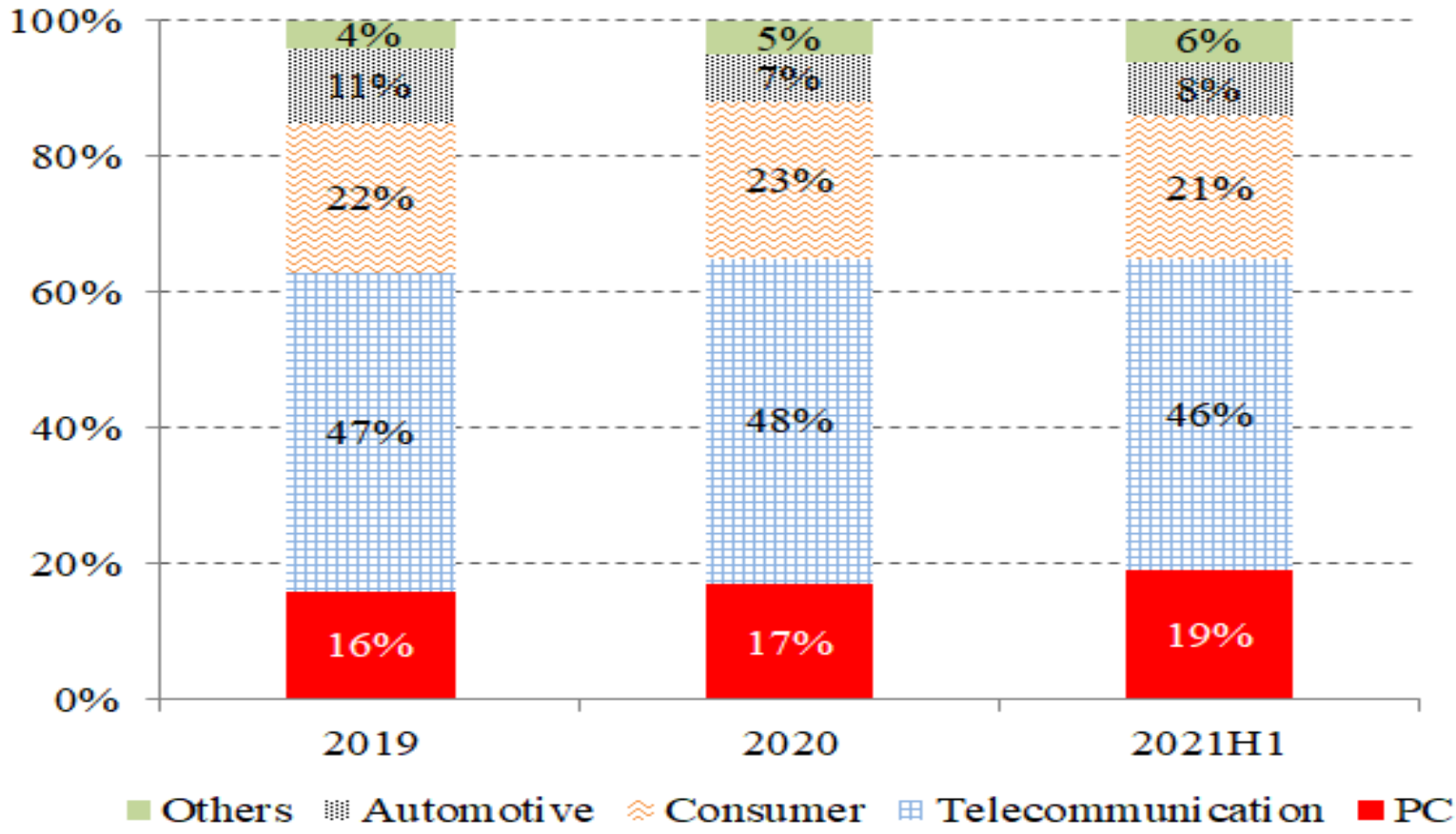
Quarterly Operation Profits in a Year



- **Operation profits in 20Q4 were increasing NTD 168.3 Mn from 20Q3:**
  Ring sales of telecom, NBs, game consoles, automotive electronics, and etc. lifted 20Q4 operation profits, matching our target of consecutive quarterly operation profits growth.
- **Operation profits in 21Q1 were increasing NTD 288.0 Mn from 20Q4:**
  Because of better sales in high value products, such as high-end CPU and GPU substrates, 2021 Q1 operation profits continued to grow.
- **Operation profits in 21Q2 were increasing NTD 1,140.4 Mn from 21Q1:**
  Growing Profits can be attributed to the new IC substrate capacities at Kunshan Campus and the better product mix.

Financial Status

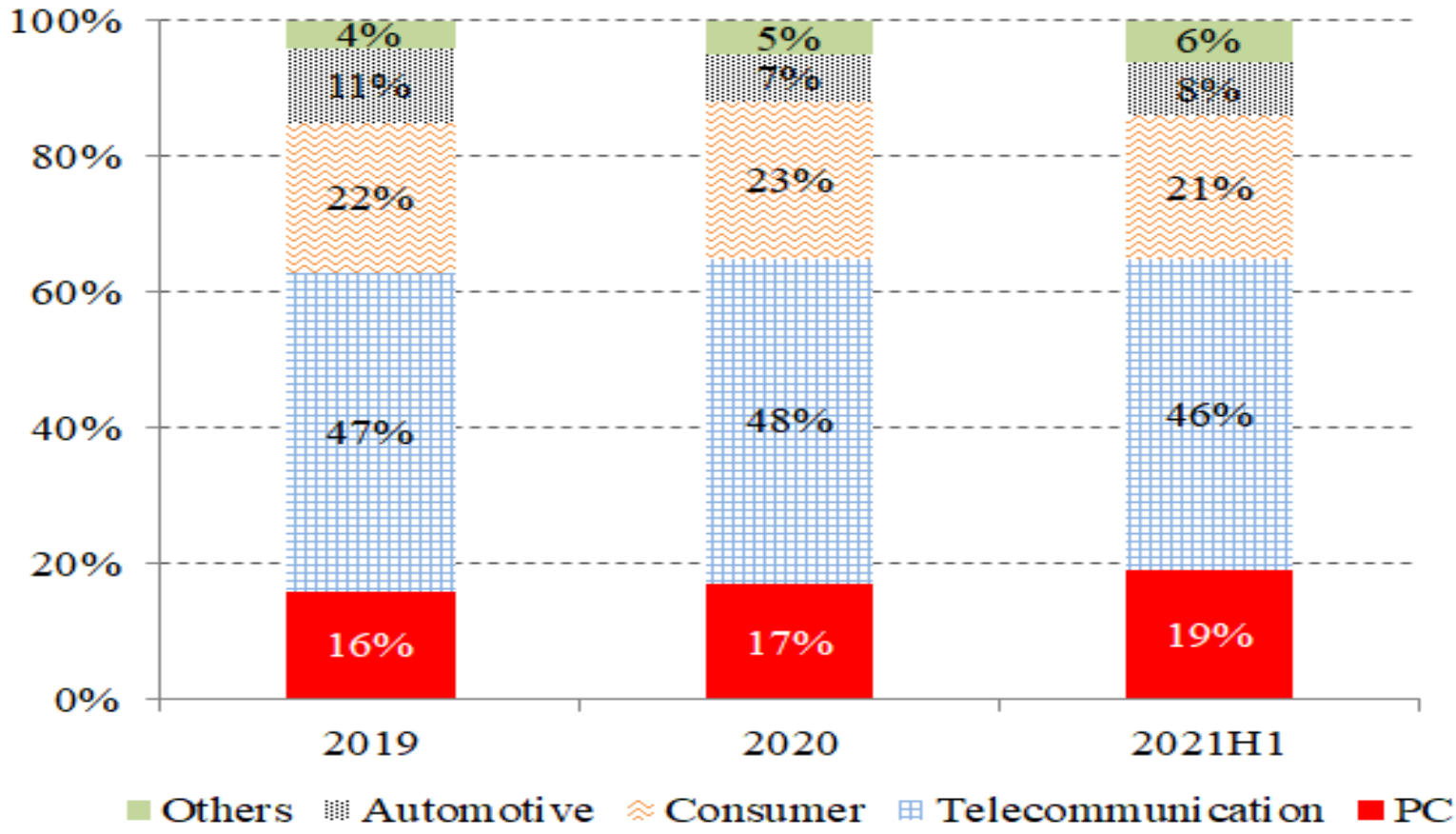
Revenue Structure(By Applications)



- Because of better demands in PCs products driven by work from home, related revenue ratios in 2021 H1 grew from 2020.
- Due to the slow season for the mobile phone and true wireless stereo, related revenue ratios in 2021 H1 declined from 2020.

Financial Status

Revenue Structure(By Applications)



- The automobile market was benefited from the easing COVID-19 situation in Europe and America, leading to our rising automotive product revenue ratio in 2021 H1.
- Nan Ya PCB actively explored the AI and HPC fields and successfully gained more high value orders from those areas. Thus, the revenue ratio of others continued to grow in 2021H1.

Future Product Development

Continue to Expand High Value Products

- **High-end ABF Substrate**
  In 2021, not only will we continue to launch substrates for the CPU, GPU, and high-end telecom processor, but also expand our market share in AI and HPC products. Additionally, increases in the demand of automotive processors, chiplet assembling, and ongoing installation of 5G base stations are leading to greater ABF sales.

- **SiP(System in Package) Substrate**
  Given the trend of heterogeneous integration remains, SiP technologies will be applied to all sorts of mobile devices. We will continue to produce SiP substrates for new generation wearable devices, camera modules in high-end smartphones, AiP, and Type C controllers. Our SiP substrate sales are expected to grow.

- **HDI**
  As the designs of handset, consumer electronics, and automotive electronics are becoming sophisticated, the consumption of high value HDI is increasing. Thus, we will roll out HDI for new generation memories, solid state drive, and infotainment systems to meet the growing demands in premium NBs and automobiles to boost our profits. Also, for the increasing demands in 5G infrastructures, the mother board sales in high-end servers and small cells are expected grow annually.

Operational Goals
Management Guidelines

- Cultivating R&D and manufacturing technology talents.
- Launching substrates for CPUs, GPUs, high-end telecom equipment, and HPC products to lift the sales ratio of high-end products.
- Continuing to apply AI to manufacturing management, implementing intelligent production, and optimizing manufacturing conditions to improve the yield rate and efficiency.
- Increasing capacities via debottleneck at Jinshing Campus before the end of 2021 and mass production in 2022 Q1. Finishing ABF substrate expansion at Shulin Campus before the end of 2022 and mass production in 2023 Q1.
- Will launch new IC substrate capacity expansion plans to increase market share and targeting quarter on quarter profit growth.

Thank You